



# PRODUCTION INFORMATION LETTER

---

PIL CRP/05/1014  
Notification Date 06/13/2005

---

**MOLDING MATERIAL IMPROVEMENT FOR SO NARROW PREPLATED PACKAGES**

**CRP - Corporate Quality Assurance**

**PIL CRP/05/1014 - Notification Date 06/13/2005**

Production process involved	Molding		
Production process details	Generic		
Description	Addition of 0.1% of adhesion promoter in the resin		
Forecasted date of implementation	01-Jul-2005		
Forecasted date of samples for customer	01-Jul-2005		
Forecasted date for <b>STMicroelectronics</b> change Qualification Plan results availability	15-Jun-2005		
Description of qualification program	See Attached Qualification Plan		
Involved ST facilities	Bouskoura, Muar and Shenzhen assembly plants		
Process Owner	Carlo Cognetti		Jun.02 ,05
Corporate Quality Manager	Robert Sangy		Date: Jun.02 ,05

Reason:

Following the recommendation of our Molding compound supplier, we have decided to slightly modify the composition of the molding compound to solve glueability issues encountered by some customers using Solder wave process.

Change description:

The glueability improvement is achieved by adding 0.1% of adhesive promoter to the existing molding compound.

The modified molding compound has been validated through standard assembly control tests and standard reliability tests, all tests passed.

The control of endurance to soldering heat has been done in accordance with the IPC/JEDEC 020-C standard.

Effect of change:

It was determined that the implemented change has no other effect on the performance of the components than improving the capability to link with typical adhesive used for package mounting prior to wave soldering.

The MSL of all involved products remain unchanged.

The modified molding compound allows ST components in SO narrow packages to be compliant with IPC SM-817 standard.

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics.

All other names are the property of their respective owners

© 2005 STMicroelectronics - All rights reserved.

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -  
Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)

